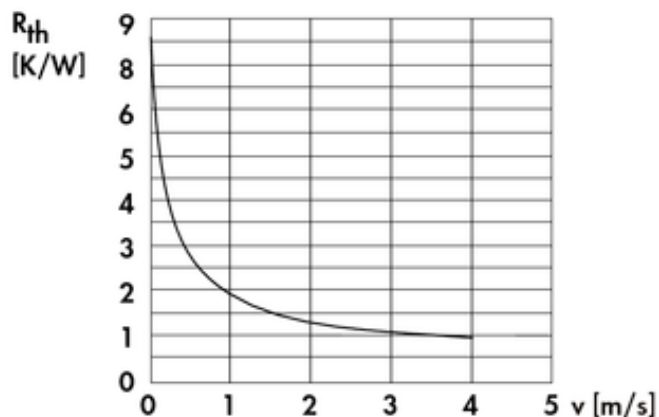
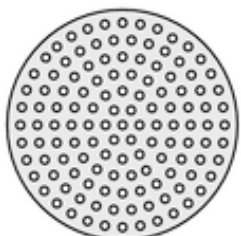
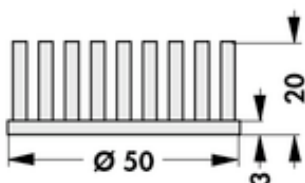
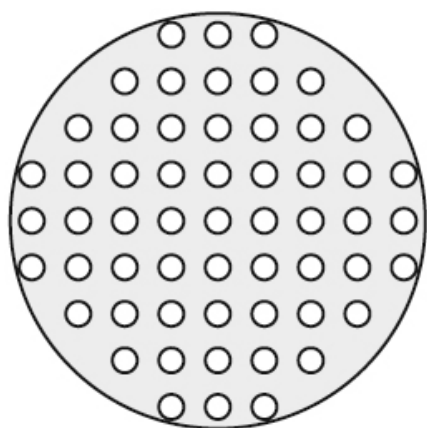


Pin heatsinks / **ICK S R 50 x 20**



Ø 50 x 20 mm, pin heatsinks round

Parameters of article ICK S R 50 x 20

| | |
|------------------------------------|--|
| Bauform | Rund |
| R_{th} [K/W] | <i>i</i> 8.55 |
| dissipation loss [W] | <i>i</i> 9.8 |
| mounting method | therm. conductive foil / therm. cond. adhesive |
| socket | universal |
| suitable for processor type | universal |
| Ø [mm] | <i>i</i> 50 |
| height [mm] | 20 |
| plate thickness [mm] | 3 |
| weight [g] | 34.39 |

Accessories/ related articles

Thermally conductive foil both sides adhesive / **WLFT 404 D 50**

Thermally conductive foil both sides adhesive / **WLFT 405 D 50**